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<<微机电系统基础>>

图书基本信息

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内容概要

本书全面论述了微机电系统（MEMS）的基础知识，涵盖了MEMS技术的主要方面，同时引用了经典的MEMS研究论文和前沿的技术论文，为学生深入学习MEMS技术提供了指引。

书中提炼出了四个典型的传感器实例：惯性传感器、压力传感器、流量传感器和触觉传感器，并介绍了利用不同原理、材料和工艺制造这些传感器的方法，既便于比较，又可以启发学生的创新意识并提高创新能力。

本书被美国斯坦福大学、伊利诺伊大学等选为教材。

作者简介

Chang Liu(刘昶)美国西北大学工程学院终身教授。

他领导的西北大学MED×实验室主要的科研方向为传感器、仿生传感器、微机电系统和纳米加工技术、流体传感器、触觉传感器及各种传感器的应用。

他同时也是西北大学超净加工(cleanroom) NuFab的主任。

他于1996年在美国加州理工学院电机系获得博士学位，是中国大陆地区留美学习微机电系统并在美国大学担任教授职位的第一人。

之后他一直在美国从事微机电系统和传感器方面的科研和教学工作。

加入西北大学前，刘昶还曾任教于美国伊利诺伊大学香槟分校并获终身教职(1996-2007)。

赴美前他曾就读于中国北京清华大学精密仪器系。

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